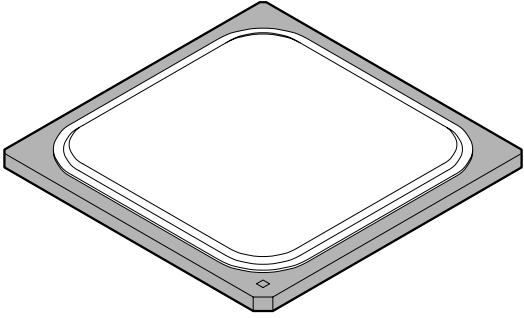
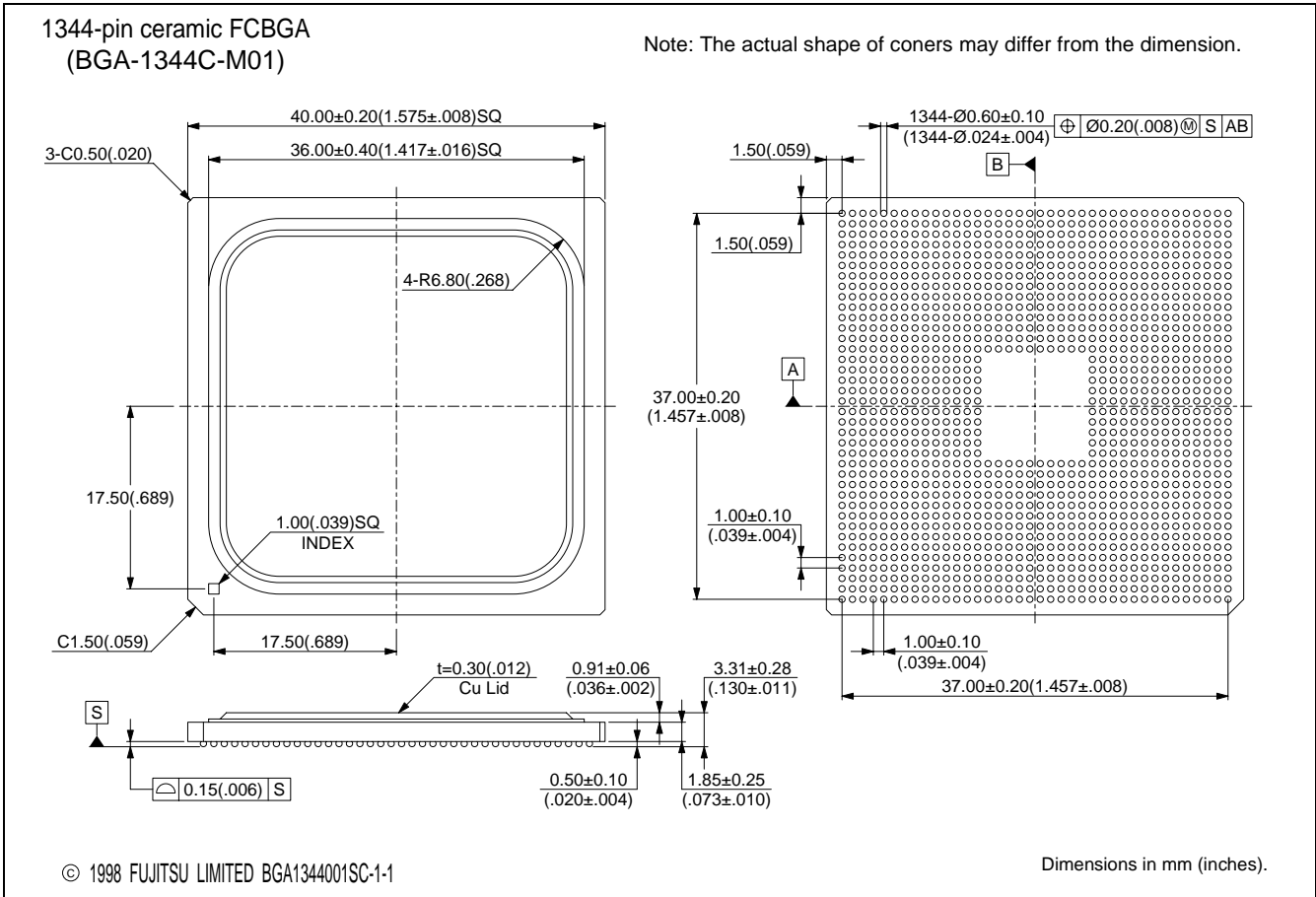


**BGA-1344C-M01**

<p>1344-pin cerami FCBGA</p>  <p>(BGA-1344C-M01)</p>	Lead pitch	1.00 mm
	Package width × package length	40.00 × 40.00 mm
	Lead shape	Ball
	Sealing method	Under fill
	Mounting height	3.59 mm Max



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